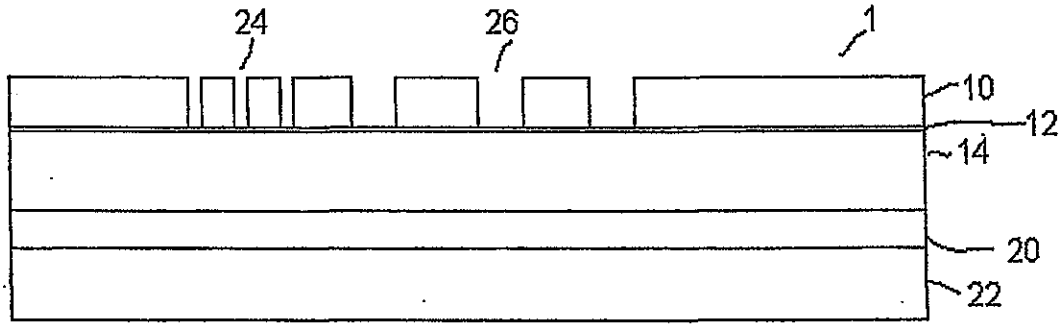



Fig. 1a (Prior Art)

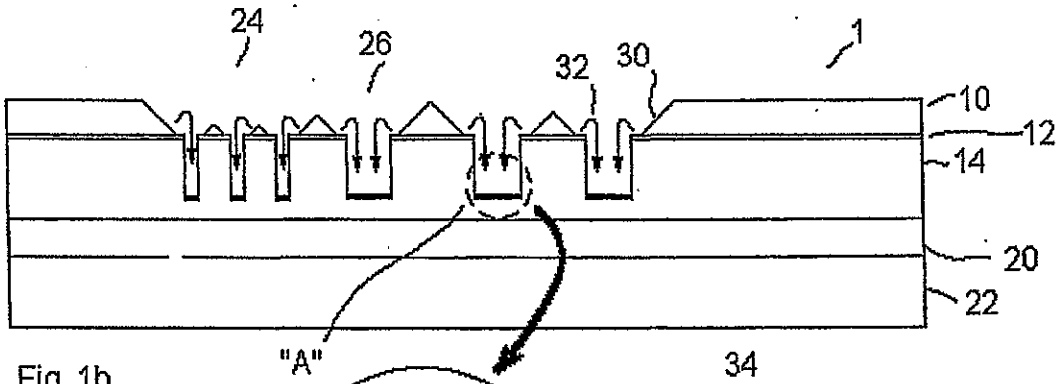



Fig. 1b
(Prior Art)

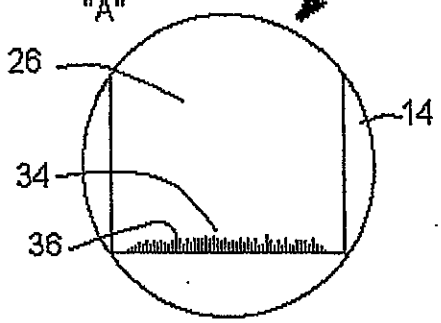



Fig. 1c
(Prior Art)

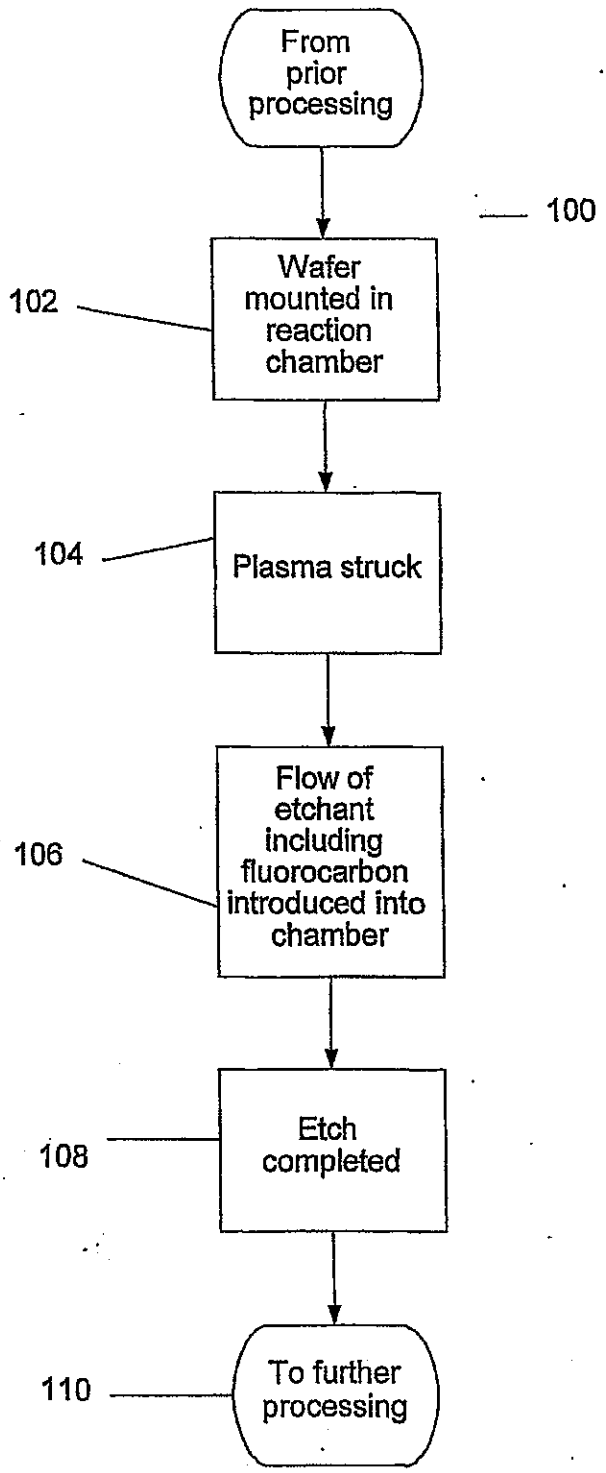

From prior processing
100
Wafer mounted in reaction chamber
102
Plasma struck
104
Flow of etchant including fluorocarbon introduced into chamber
106
Etch completed
108
To further processing
110

Fig. 2

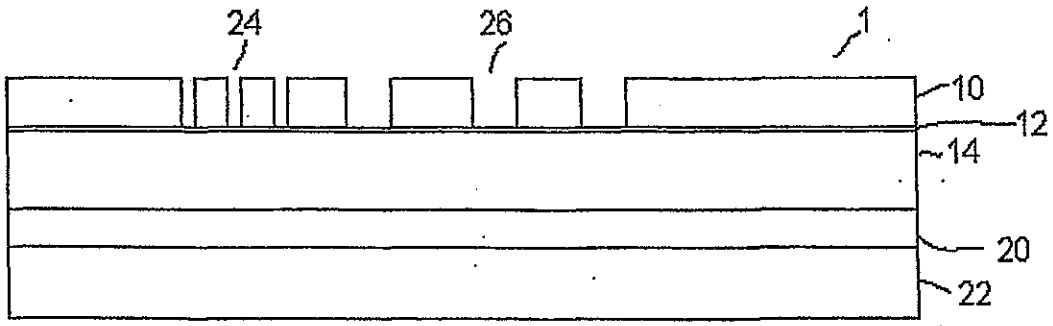



Fig. 3a

Fig. 3b

